

Patent Application No. 10/000,000

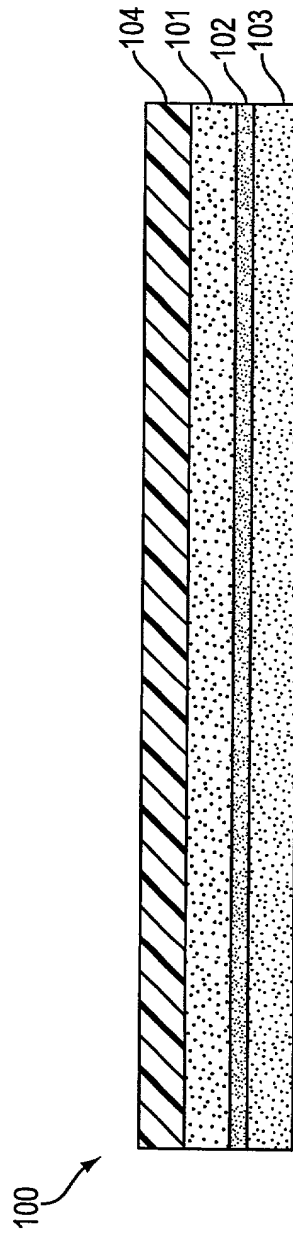


FIG. 1

Express Mail Number
EL7517772264S

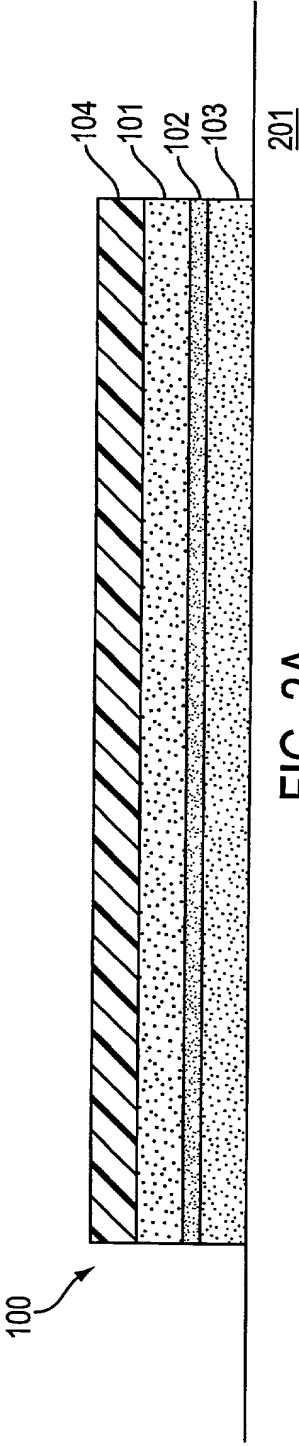


FIG. 2A

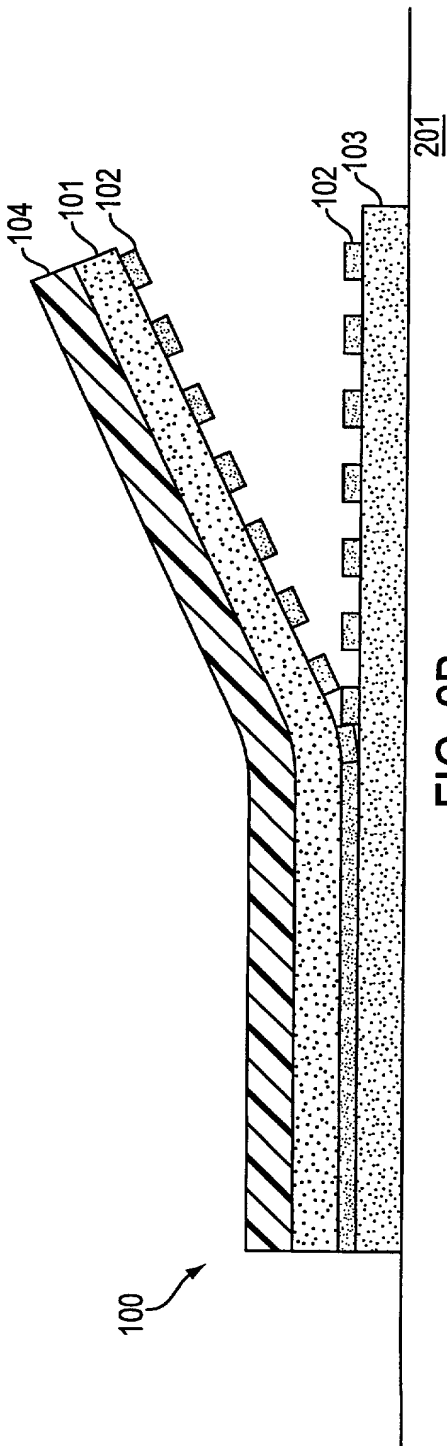


FIG. 2B

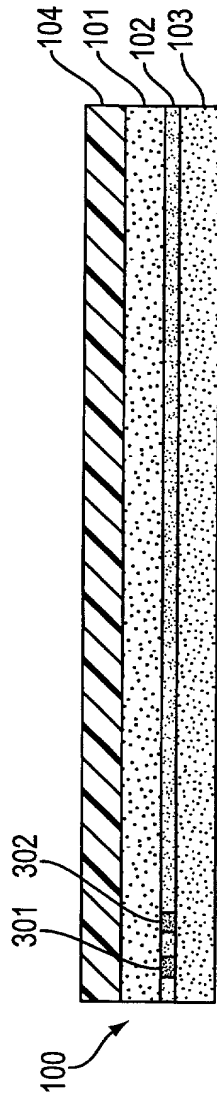


FIG. 3A

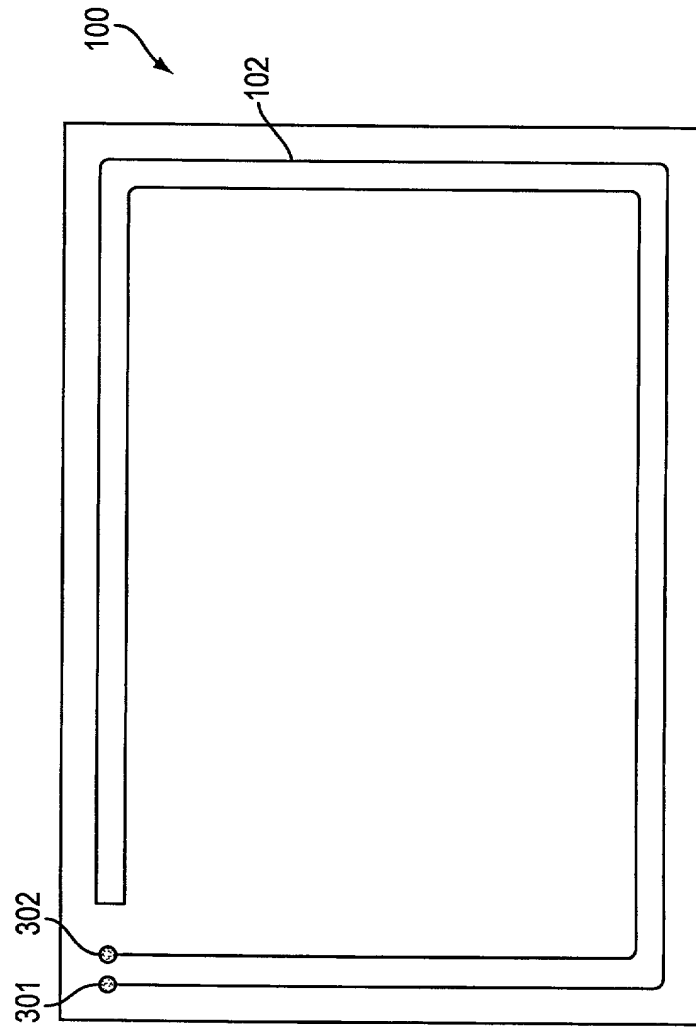


FIG. 3B

FIG. 4A is a cross-sectional view of a device 100, showing a substrate 101 with a layer 102 and a layer 103. A layer 104 is formed on top of layer 102. A layer 301 is formed on top of layer 104. A layer 401 is formed on top of layer 301. A layer 402 is formed on top of layer 401. A layer 302 is formed on top of layer 402. A layer 100 is formed on top of layer 302.

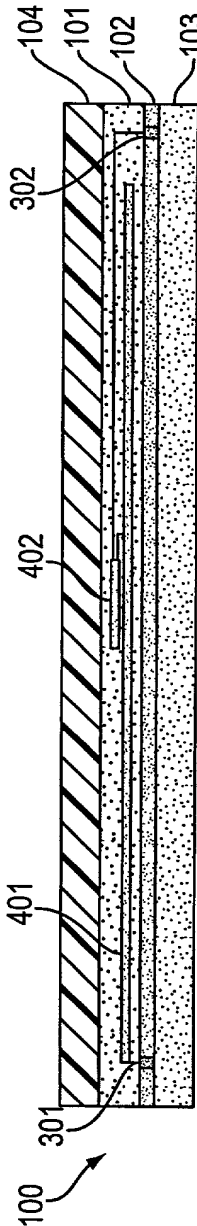


FIG. 4A

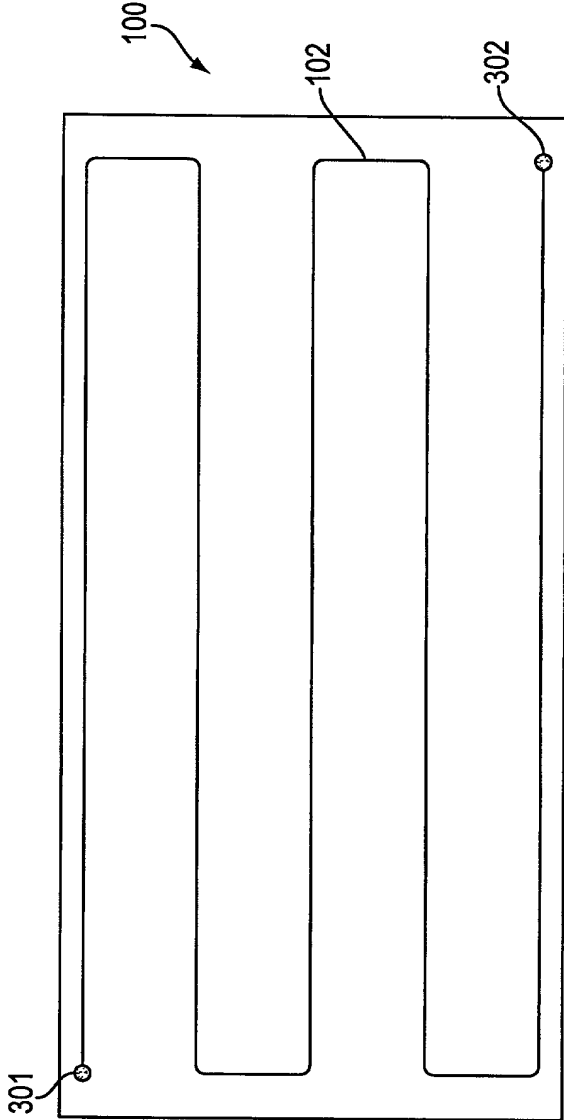


FIG. 4B

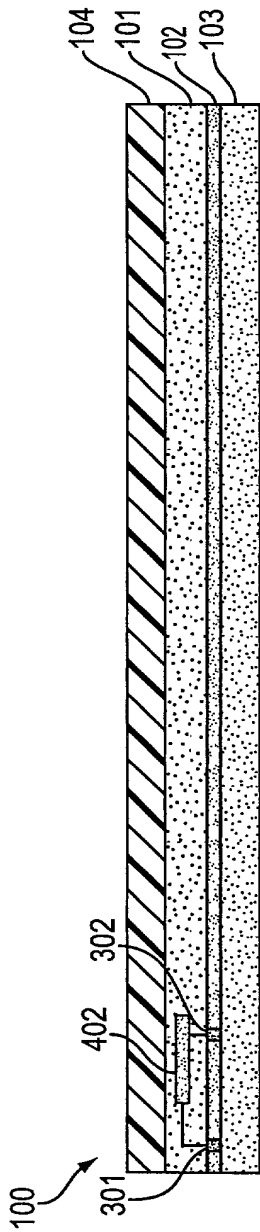


FIG. 5A

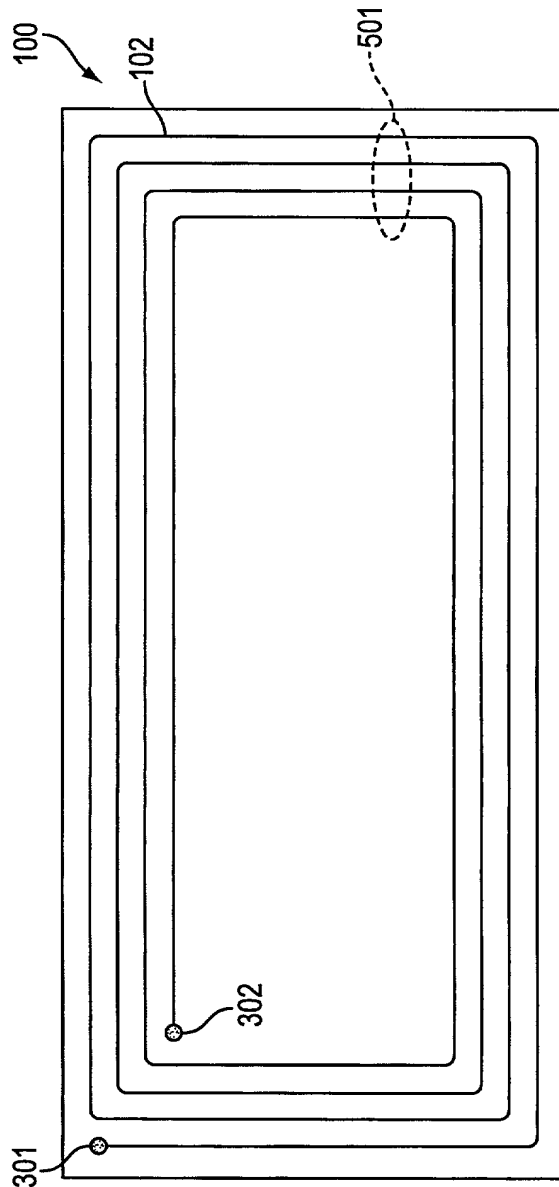


FIG. 5B

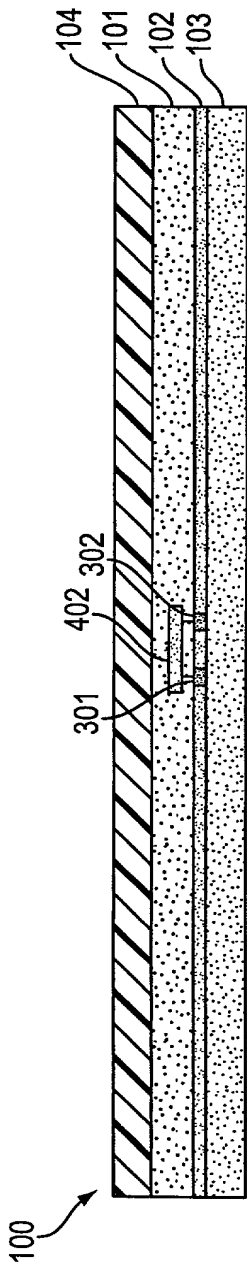


FIG. 6A

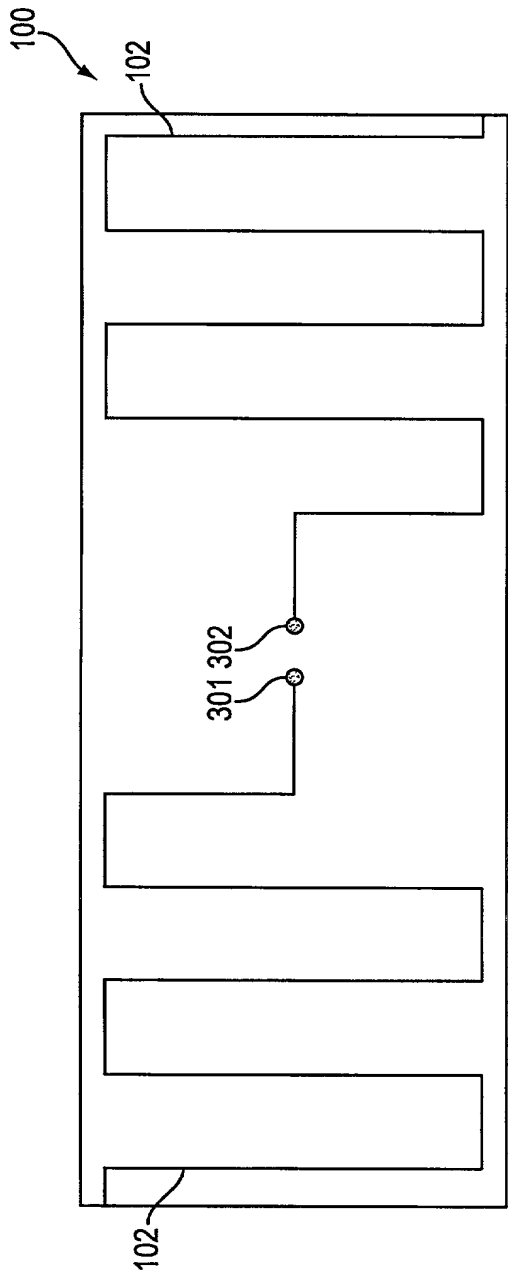


FIG. 6B

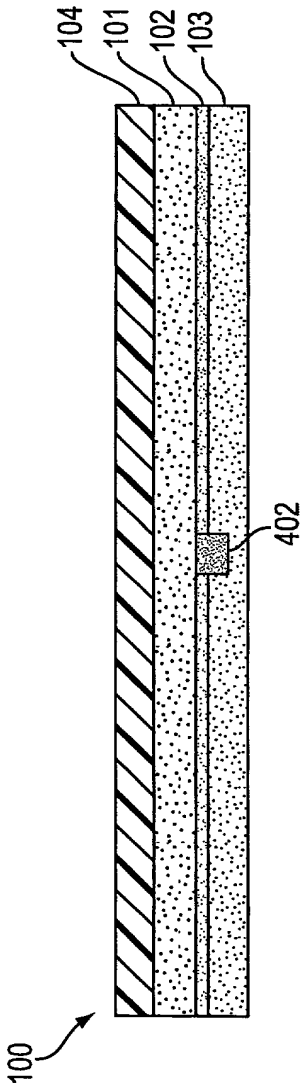


FIG. 7A

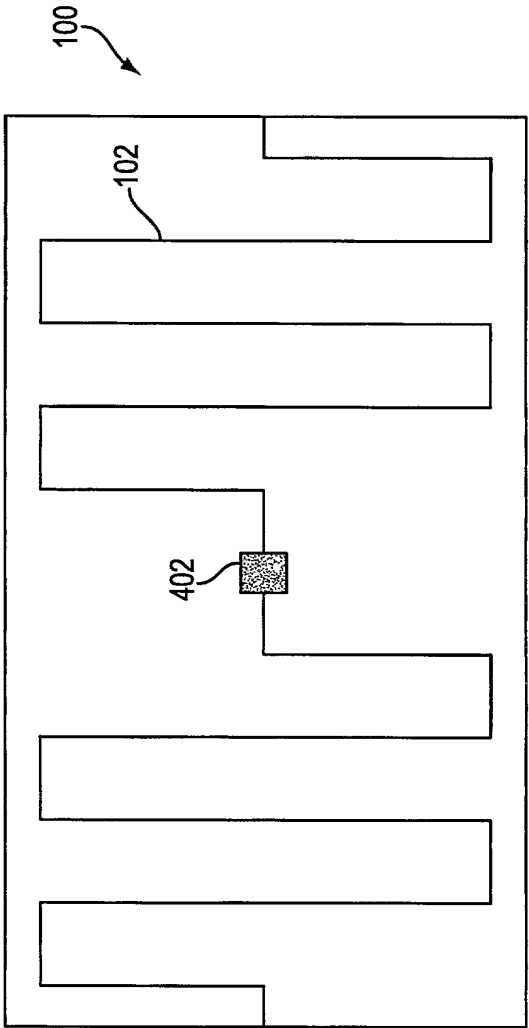


FIG. 7B

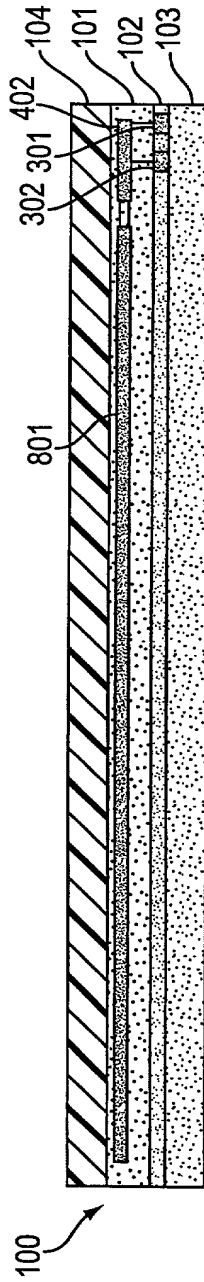


FIG. 8A

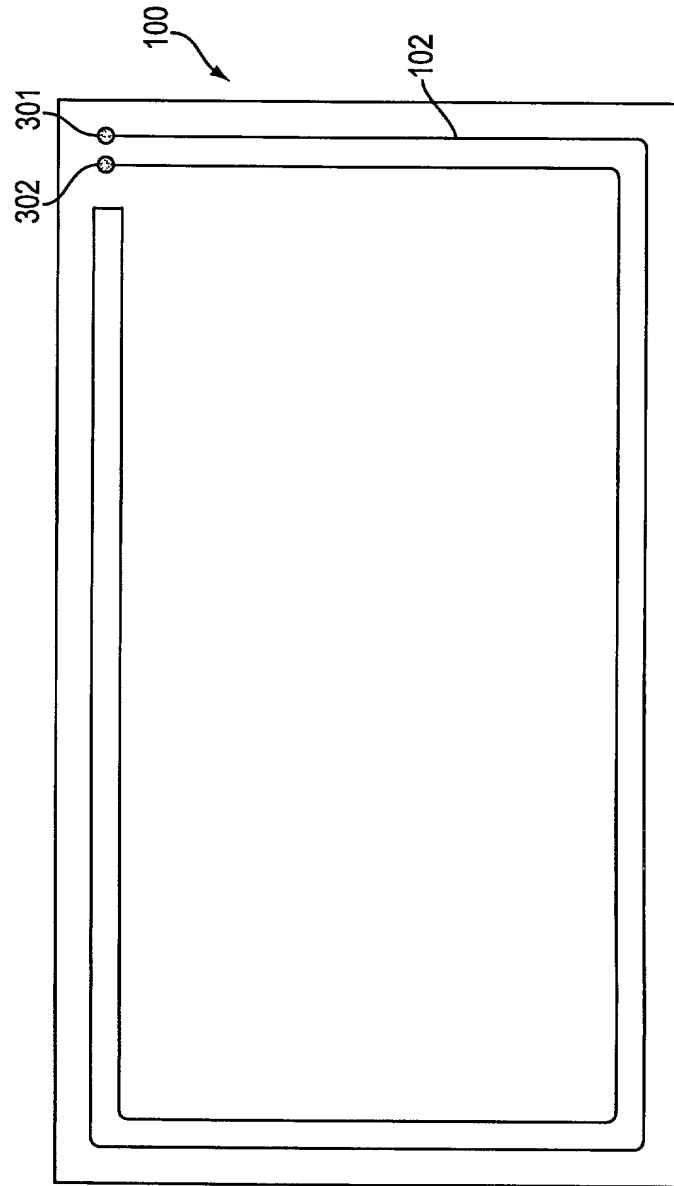


FIG. 8B

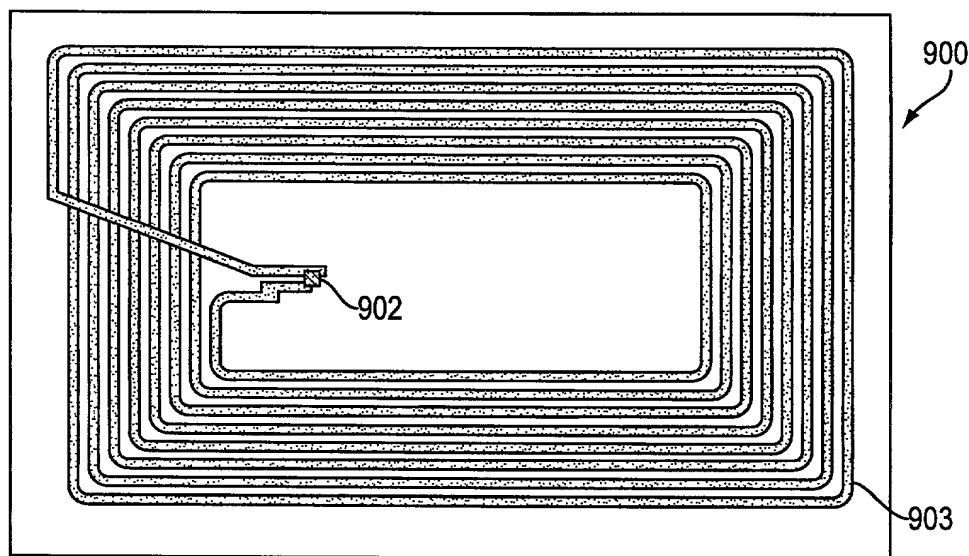


FIG. 9A

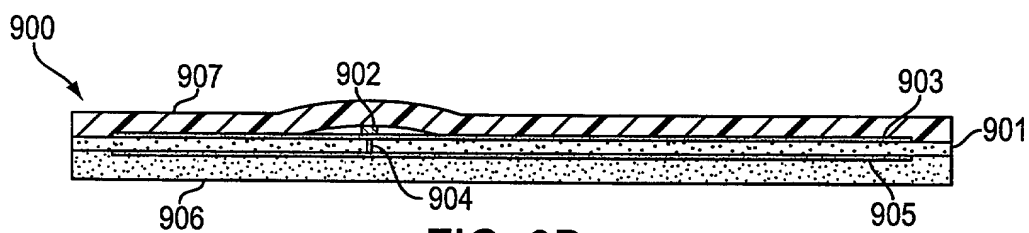


FIG. 9B

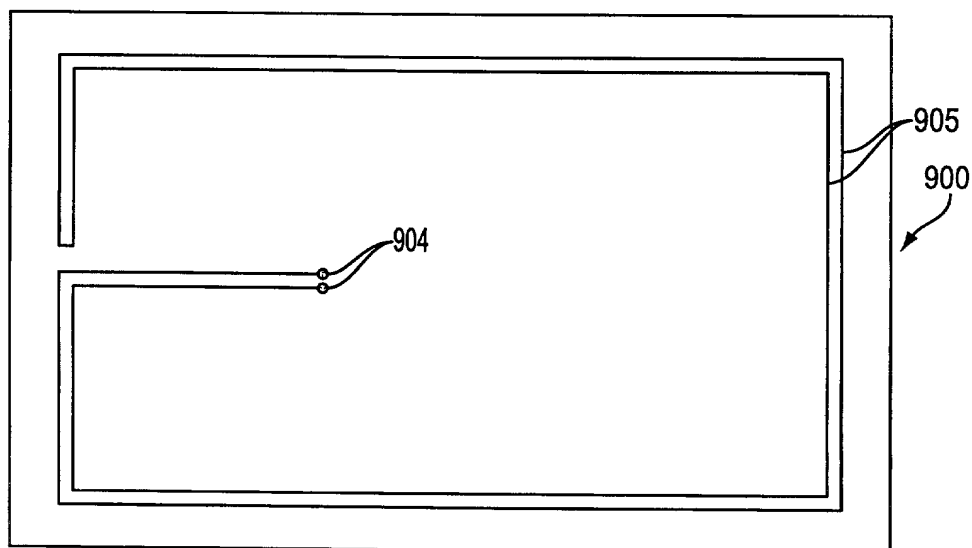


FIG. 9C

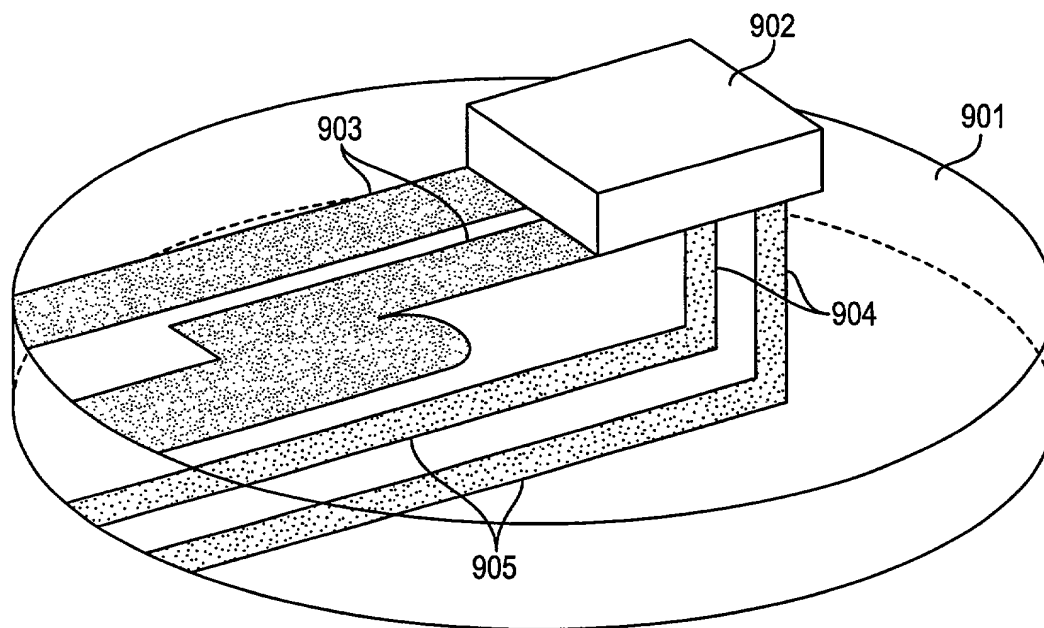


FIG. 9D

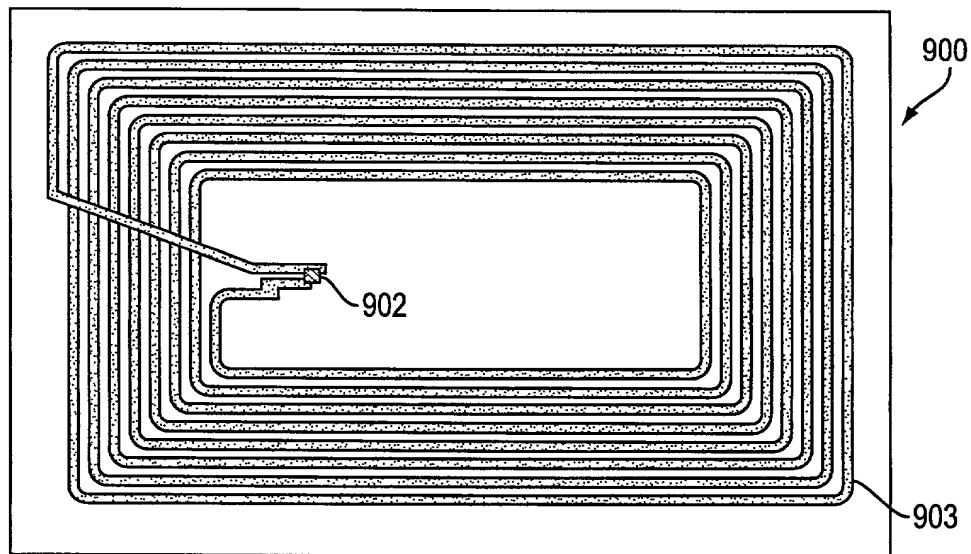


FIG. 10A

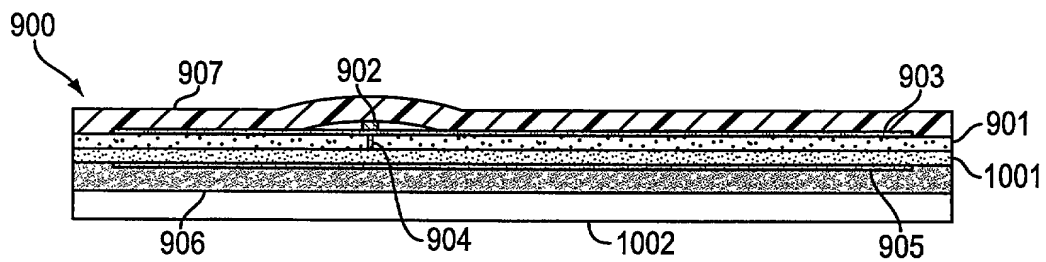


FIG. 10B

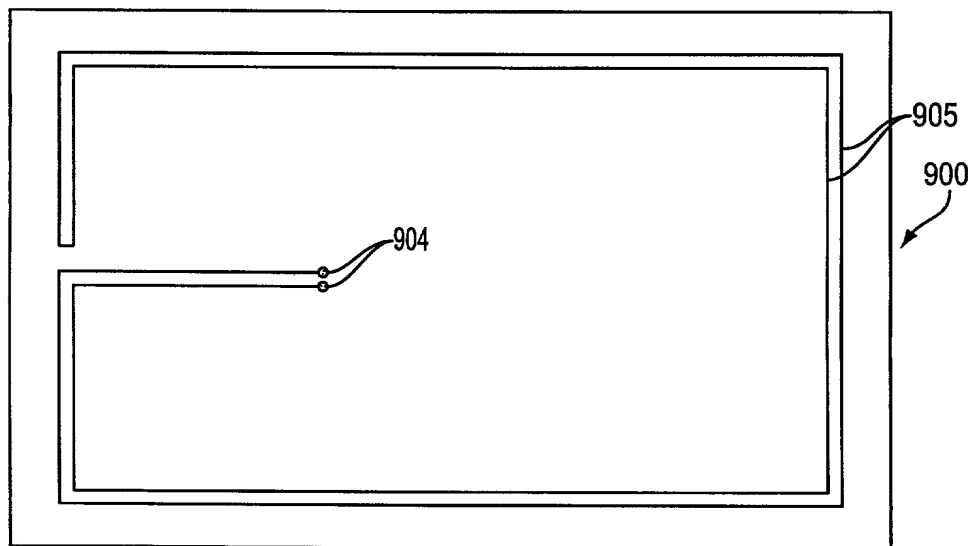


FIG. 10C

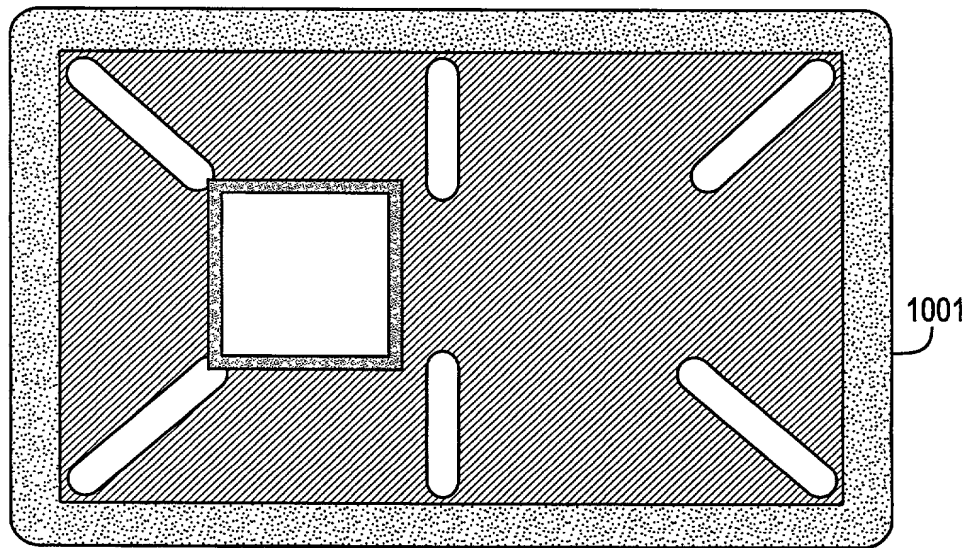


FIG. 10D

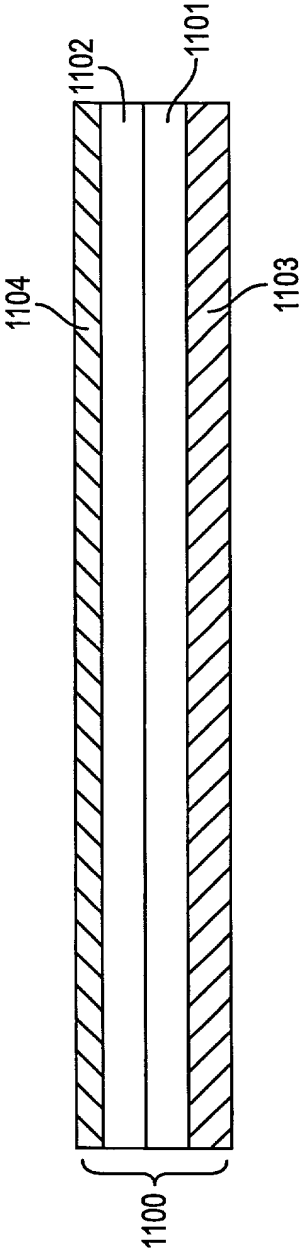


FIG. 11

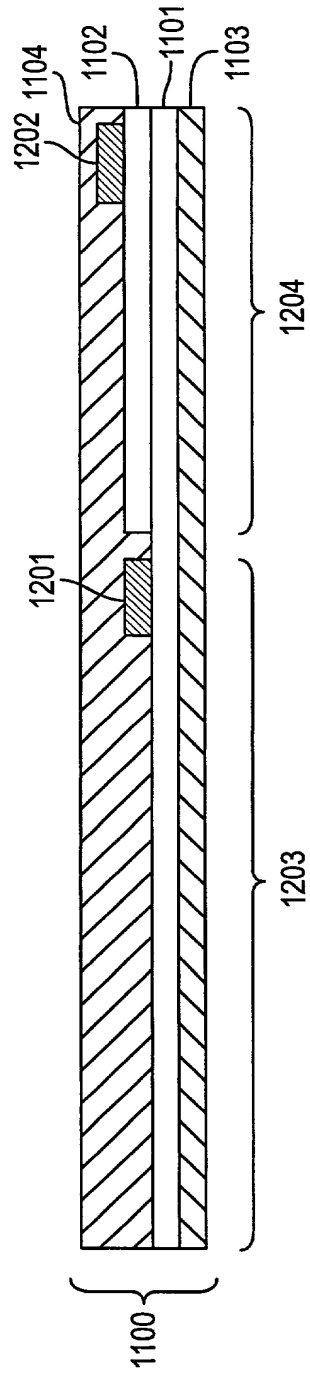


FIG. 12A-1

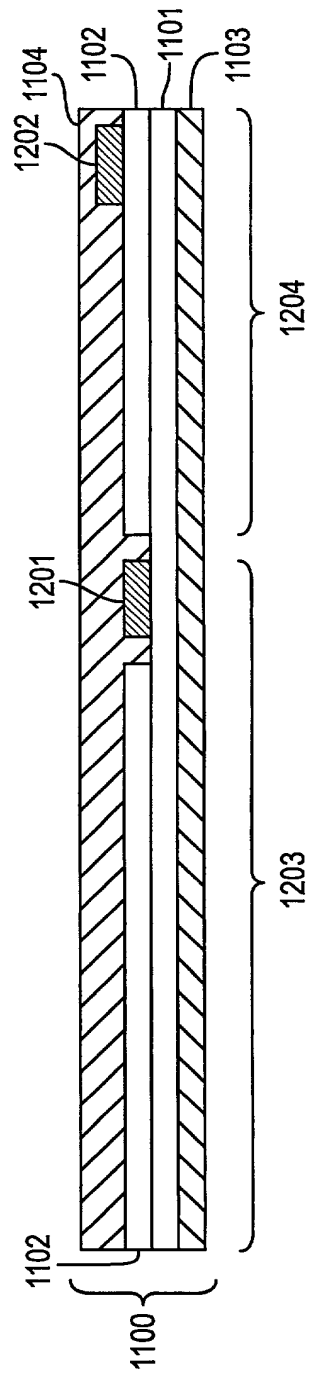


FIG. 12A-2

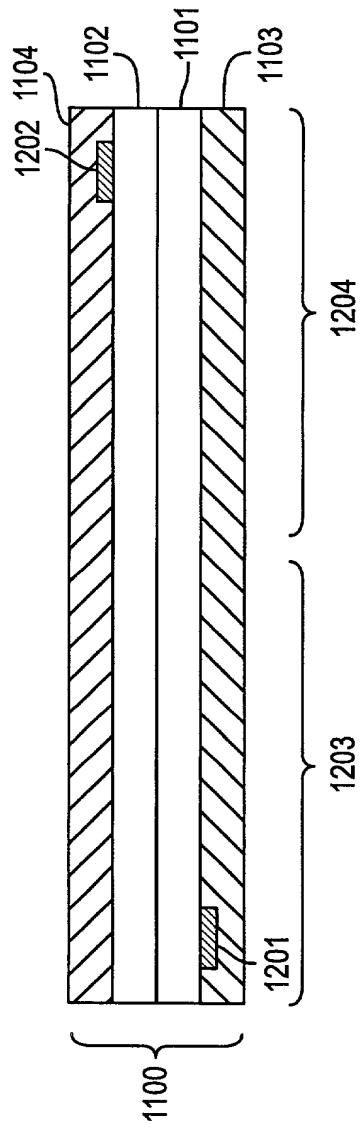


FIG. 12B

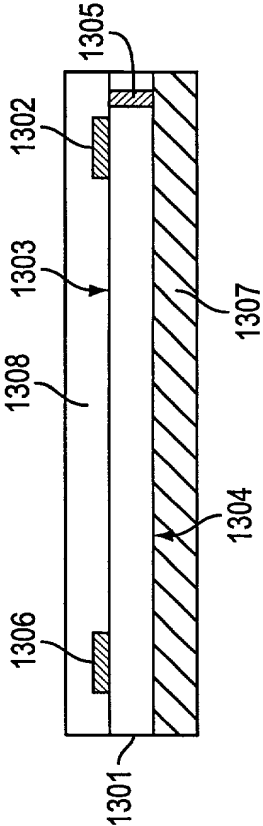


FIG. 13